

NOTES:

SPECIFICATION:

1. CURRENT RATING: 3.0A MAX
2. DIELECTRIC WITHSTAND VOLTAGE: 100VAC
3. TEMPERATURE RANGE: -30 °C ~ 85 °C
4. CONTACT RESISTANCE: 40 MILLIONHM MAX
5. INSULATION RESISTANCE: 100 MEGOHMS MIN.
6. INSERTION FORCE : 5N~20N
7. UNMATING FORCE: 8N~20N
8. DURABILITY:5000 CYCLES

PIN ASSIGNMENT

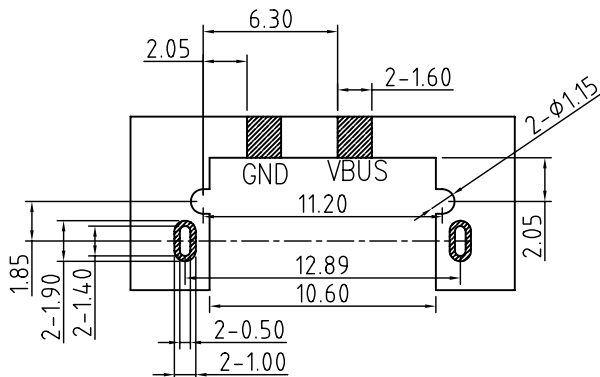
| | | |
|-------------|---------|-------|
| PIN NO. | A12&B12 | A4&B4 |
| SINGAL NAME | GND | VBUS |
| PCB PAD NO. | C1 | C2 |

组装示意图

INTERFACE(FRONT VIEW)

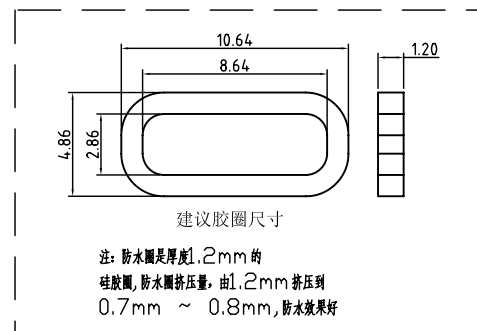
| | | | | | | | | | | | |
|-----|-----|-----|------|----|----|----|----|----|------|-----|-----|
| A1 | A2 | A3 | A4 | A5 | A6 | A7 | A8 | A9 | A10 | A11 | A12 |
| | | | VBUS | | | | | | VBUS | | GND |
| GND | | | | | | | | | | | |
| B12 | B11 | B10 | B9 | B8 | B7 | B6 | B5 | B4 | B3 | B2 | B1 |

| | | | | |
|------|----------|------|--|--|
| 5 | Shell2 | 1 | SUS304 Ni Plating T=0.20mm | Ni:40~120u"; |
| 4 | Shell1 | 1 | SUS304 Ni Plating T=0.3mm | Ni:40~120u"; |
| 3 | Housing2 | 1 | LCP(G.F30%) | |
| 2 | Contact | 4 | Phosphor bronze C5210R-EH Au/Ni Plating T=0.20mm | Ni:40~160u"; Au:CONTACT AREA:3u", OTHER AREA:G/F |
| 1 | Housing | 1 | PA9T (G.F30%) | |
| ITEM | PARTNAME | Q'TY | FINISH | NOTE |



RECOMMENDED PCB LAYOUT(TOP VIEW)

THICKNESS T=1.0mm
DEFAULT TOLERANCE+/-0.05



建议胶圈尺寸

注: 防水圈是厚度1.2mm的
硅胶圈, 防水圈挤压力, 由1.2mm挤压到
0.7mm ~ 0.8mm, 防水效果好



深圳市华宇创精密电子有限公司

| | | | |
|--|--------------------|----------------------|---|
| TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2' X.X' ±0.5' | DRAWN BY : 陈一鸣 | DATE : 2014-02-23 | PART NAME: USB TYPE C 母座防水2P 沉板SMT 外壳两脚DIP |
| | CHECKED BY: 马跃 | DATE : 2014-02-23 | PART NO. : HYCW264-USBC02-218B |
| UNIT: mm [inch] SCALE:1:1 SIZE: A4 | APPROVED BY: 邱敏 | DATE : 2014-02-23 | DRAW NO. : HYC-2105251651 |
| | | | SHEET NO. : 1 OF 1 |